

B2
5. (Amended) A method of joining the leads of a tape carrier package (TCP) to the electrodes of a thin film transistor (TFT) substrate in a liquid crystal display, the method comprising:

pre-forming at least one of said leads or at least one of said electrodes to have a pre-connection shape including a straight region and an oblique region;

overlapping said electrodes with said leads; and

electrically connecting said electrodes and leads through an anisotropic conducting film by thermocompression bonding, which causes said preformed lead or electrode to be substantially aligned with the respective lead or electrode to which it is connected.

B2-cont
6. (Amended) A TFT substrate comprising:

a plurality of electrode terminals arranged in a comb teeth manner along one end face of the TFT substrate and connected to a plurality of lead terminals of a film carrier through an anisotropic conductive film;

wherein at least one of the electrode terminals of said TFT substrate is formed in such a manner as to have a pre-connection shape including a parallel straight region and a bent region in an overlapping area of said TFT substrate with said film carrier such that a respective lead terminal of the film carrier will be substantially aligned to the predetermined shape of the at least one electrode when connected thereto.

7. (Amended) A film carrier comprising

a plurality of lead terminals being connected to a plurality of electrode terminals arranged in a comb teeth manner along one end face of a TFT substrate through an anisotropic conductive film;